



Product Change Notification

Change Notification #: 118790-00
Change Title: Select Intel® SSD D5-P5316 Series
PCN 118790-00, Product Material,
Adding Second Source Components
Date of Publication: December 13, 2021

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	February 12, 2022
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Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

1. Adding second-source FETs, diodes and voltage regulator to all D5-P5316 SKUs in order to ensure supply continuity for the product lines.

Type	Use Case	Current Supplier (IPN)	Alternate Supplier (IPN)	Affected MM#s
Circuit Protection Diode	3.3V Aux	Diodes Inc (G24376-001)	Nexperia (M59256-001)	All MM#s in this PCN
MOSFET	Vcap Switch	Diodes Inc (J53658-001)	Toshiba (M59118-001)	
MOSFET	SMBUS LVL Shifter FET	On Semi (G50657-001)	Diodes Inc (K41819-001)	
		Nexperia (H75826-001)		
MOSFET	SMBUS Isolation FET	Nexperia (H75826-001)	Toshiba (M67972-001)	
		Diodes Inc (K41819-001)		
Voltage Regulator	-	MPS (J78028-001)	MPS (J78028-002)	

2. Adding second-source FETs to D5-P5316 E1.L SKUs in order to ensure supply continuity for the product lines.

Type	Use Case	Current Supplier (IPN)	Alternate Supplier (IPN)	Affected MM#s
MOSFET	LED Switch	On Semi (E76744-001)	Toshiba (M58901-001)	99AA1T, 99AA1V

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers, however Intel plans to ship product based on supply availability. As such, Intel will have a soft cut-in for the second-source components. Please contact your local Intel Field Sales Rep if you have any further questions about these changes

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD D5-P5316 Series (15.3TB, 2.5in PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPF2NV153TZN1	99AA1N
Intel® SSD D5-P5316 Series (30.7TB, 2.5in PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPF2NV307TZN1	99AA1P
Intel® SSD D5-P5316 Series (15.3TB, EDSFF L 9.5mm PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPFWNV153TZN1	99AA1T
Intel® SSD D5-P5316 Series (30.7TB, EDSFF L 9.5mm PCIe 4.0 x4, 3D4, QLC) Generic No OPAL Single Pack	SSDPFWNV307TZN1	99AA1V

PCN Revision History:

Date of Revision:

December 13, 2021

Revision Number:

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Reason:

Originally Published PCN



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118790-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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